Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	60MHz
Connectivity	I²C, Microwire, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	38
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc2157fbd100-551

Table 2. Pin description LPC2157 *…continued*

Symbol	Pin	Type	Description
P0[15]/RI1/ EINT2/AD1[5]	28[4]	I/O	**P0[15] —** General purpose input/output digital pin (GPIO).
		I	**RI1 —** Ring Indicator input for UART1.
		I	**EINT2 —** External interrupt 2 input.
		I	**AD1[5] —** ADC 1, input 5.
P0[16]/EINT0/ MAT0[2]/CAP0[2]	29[2]	I/O	**P0[16] —** General purpose input/output digital pin (GPIO).
		I	**EINT0 —** External interrupt 0 input.
		O	**MAT0[2] —** Match output for Timer 0, channel 2.
		I	**CAP0[2] —** Capture input for Timer 0, channel 2.
P0[17]/CAP1[2]/ SCK1/MAT1[2]	30[1]	I/O	**P0[17] —** General purpose input/output digital pin (GPIO).
		I	**CAP1[2] —** Capture input for Timer 1, channel 2.
		I/O	**SCK1 —** Serial Clock for SSP. Clock output from master or input to slave.
		O	**MAT1[2] —** Match output for Timer 1, channel 2.
P0[18]/CAP1[3]/ MISO1/MAT1[3]	79[1]	I/O	**P0[18] —** General purpose input/output digital pin (GPIO).
		I	**CAP1[3] —** Capture input for Timer 1, channel 3.
		I/O	**MISO1 —** Master In Slave Out for SSP. Data input to SPI master or data output from SSP slave.
		O	**MAT1[3] —** Match output for Timer 1, channel 3.
P0[19]/MAT1[2]/ MOSI1/CAP1[2]	80[1]	I/O	**P0[19] —** General purpose input/output digital pin (GPIO).
		O	**MAT1[2] —** Match output for Timer 1, channel 2.
		I/O	**MOSI1 —** Master Out Slave In for SSP. Data output from SSP master or data input to SSP slave.
		I	**CAP1[2] —** Capture input for Timer 1, channel 2.
P0[20]/MAT1[3]/ SSEL1/EINT3	81[2]	I/O	**P0[20] —** General purpose input/output digital pin (GPIO).
		O	**MAT1[3] —** Match output for Timer 1, channel 3.
		I	**SSEL1 —** Slave Select for SSP. Selects the SSP interface as a slave.
		I	**EINT3 —** External interrupt 3 input.
P0[21]/PWM5/ AD1[6]/CAP1[3]	91[4]	I/O	**P0[21] —** General purpose input/output digital pin (GPIO).
		O	**PWM5 —** Pulse Width Modulator output 5.
		I	**AD1[6] —** ADC 1, input 6.
		I	**CAP1[3] —** Capture input for Timer 1, channel 3.
P0[22]/AD1[7]/ CAP0[0]/ MAT0[0]	92[4]	I/O	**P0[22] —** General purpose input/output digital pin (GPIO).
		I	**AD1[7] —** ADC 1, input 7.
		I	**CAP0[0] —** Capture input for Timer 0, channel 0.
		O	**MAT0[0] —** Match output for Timer 0, channel 0.
P0[23]	84[1]	I/O	**P0[23] —** General purpose input/output digital pin (GPIO).
P0[25]/AD0[4]/ AOUT	97[5]	I/O	**P0[25] —** General purpose input/output digital pin (GPIO).
		I	**AD0[4] —** ADC 0, input 4.
		O	**AOUT —** DAC output.
P0[26]/AD0[5]	98[7]	I/O	**P0[26] —** General purpose input/output digital pin (GPIO).
		I	**AD0[5] —** ADC 0, input 5. This analog input is always connected to its pin.

Table 2. Pin description LPC2157 *…continued*

Symbol	Pin	Type	Description
$\overline{\text{RESET}}$	83[8]	I	**External reset input:** A LOW on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. TTL with hysteresis, 5 V tolerant.
XTAL1	88[9]	O	Input from the oscillator amplifier.
XTAL2	87[9]	I	Output to the oscillator circuit and internal clock generator circuits.
RTCX1	93[9]	I	Input to the RTC oscillator circuit.
RTCX2	94[9]	O	Output from the RTC oscillator circuit.
V_{SS}	6, 13, 32, 39, 40, 85, 95	I	**Ground:** 0 V reference.
V_{DD}	11, 27, 33	I	**3.3 V power supply:** This is the power supply voltage for the core and I/O ports.
V_{DDA}	96	I	**Analog 3.3 V power supply:** This should be nominally the same voltage as V_{DD} but should be isolated to minimize noise and error. This voltage is only used to power the on-chip ADC(s) and DAC.
$V_{DD(LCD)}$	38	I	**1.8 V to 5.5 V power supply:** Power supply voltage for the PCF8576D.
V_{LCD}	41	I	**LCD power supply:** LCD voltage.
VREF	89	I	**ADC reference voltage:** This should be nominally less than or equal to the V_{DD} voltage but should be isolated to minimize noise and error. Level on this pin is used as a reference for ADC(s) and DAC.
VBAT	31	I	**RTC power supply voltage:** 3.3 V on this pin supplies the power to the RTC.
SDA_LCD	34	I/O	**SDA LCD —** I^2C-bus data signal for the LCD controller.
SCL_LCD	35	I	**SCL LCD —** I^2C-bus clock signal for the LCD controller.
$\overline{\text{SYNC}}$	36	I/O	**$\overline{\text{SYNC}}$ —** cascade synchronization input/output
CLK	37	I/O	**CLK —** external clock input/output
BP0 to BP3	42 to 45	O	**BP0 to BP3:** LCD backplane outputs.
S0 to S31	46 to 77	O	**S0 to S31:** LCD segment outputs.

[1] 5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control.

[2] 5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control. If configured for an input function, this pad utilizes built-in glitch filter that blocks pulses shorter than 3 ns.

[3] Open-drain 5 V tolerant digital I/O I^2C-bus 400 kHz specification compatible pad. It requires external pull-up to provide an output functionality.

[4] 5 V tolerant pad providing digital I/O (with TTL levels and hysteresis and 10 ns slew rate control) and analog input function. If configured for an input function, this pad utilizes built-in glitch filter that blocks pulses shorter than 3 ns. When configured as an ADC input, digital section of the pad is disabled.

[5] 5 V tolerant pad providing digital I/O (with TTL levels and hysteresis and 10 ns slew rate control) and analog output function. When configured as the DAC output, digital section of the pad is disabled.

[6] 5 V tolerant pad with built-in pull-up resistor providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control. The pull-up resistor's value typically ranges from 60 kΩ to 300 kΩ.

[7] Pad is designed in accordance with the Universal Serial Bus (USB) specification, revision 2.0 (Full-speed and Low-speed mode only).

[8] 5 V tolerant pad providing digital input (with TTL levels and hysteresis) function only.

[9] Pad provides special analog functionality.

Table 3. Pin description LPC2158

Symbol	Pin	Type	Description
P0[0] to P0[31]		I/O	**Port 0:** Port 0 is a 32-bit I/O port with individual direction controls for each bit. Total of 29 pins of the Port 0 can be used as a general purpose bidirectional digital I/Os while P0[31] is output only pin. The operation of port 0 pins depends upon the pin function selected via the pin connect block. Pins P0[24], P0[26] and P0[27] are not available.
P0[0]/TXD0/ PWM1	7[1]	I/O	**P0[0] —** General purpose input/output digital pin (GPIO).
		O	**TXD0 —** Transmitter output for UART0.
		O	**PWM1 —** Pulse Width Modulator output 1.
P0[1]/RXD0/ PWM3/EINT0	9[2]	I/O	**P0[1] —** General purpose input/output digital pin (GPIO).
		I	**RXD0 —** Receiver input for UART0.
		O	**PWM3 —** Pulse Width Modulator output 3.
		I	**EINT0 —** External interrupt 0 input.
P0[2]/SCL0/ CAP0[0]	10[3]	I/O	**P0[2] —** General purpose input/output digital pin (GPIO).
		I/O	**SCL0 —** I^2C0 clock input/output. Open-drain output (for I^2C-bus compliance).
		I	**CAP0[0] —** Capture input for Timer 0, channel 0.
P0[3]/SDA0/ MAT0[0]/EINT1	14[3]	I/O	**P0[3] —** General purpose input/output digital pin (GPIO).
		I/O	**SDA0 —** I^2C0 data input/output. Open-drain output (for I^2C-bus compliance).
		O	**MAT0[0] —** Match output for Timer 0, channel 0.
		I	**EINT1 —** External interrupt 1 input.
P0[4]/SCK0/ CAP0[1]/AD0[6]	15[4]	I/O	**P0[4] —** General purpose input/output digital pin (GPIO).
		I/O	**SCK0 —** Serial clock for SPI0. SPI clock output from master or input to slave.
		I	**CAP0[1] —** Capture input for Timer 0, channel 1.
		I	**AD0[6] —** ADC 0, input 6.
P0[5]/MISO0/ MAT0[1]/AD0[7]	17[4]	I/O	**P0[5] —** General purpose input/output digital pin (GPIO).
		I/O	**MISO0 —** Master In Slave Out for SPI0. Data input to SPI master or data output from SPI slave.
		O	**MAT0[1] —** Match output for Timer 0, channel 1.
		I	**AD0[7] —** ADC 0, input 7.
P0[6]/MOSI0/ CAP0[2]/AD1[0]	18[4]	I/O	**P0[6] —** General purpose input/output digital pin (GPIO).
		I/O	**MOSI0 —** Master Out Slave In for SPI0. Data output from SPI master or data input to SPI slave.
		I	**CAP0[2] —** Capture input for Timer 0, channel 2.
		I	**AD1[0] —** ADC 1, input 0.
P0[7]/SSEL0/ PWM2/EINT2	19[2]	I/O	**P0[7] —** General purpose input/output digital pin (GPIO).
		I	**SSEL0 —** Slave Select for SPI0. Selects the SPI interface as a slave.
		O	**PWM2 —** Pulse Width Modulator output 2.
		I	**EINT2 —** External interrupt 2 input.
P0[8]/TXD1/ PWM4/AD1[1]	20[4]	I/O	**P0[8] —** General purpose input/output digital pin (GPIO).
		O	**TXD1 —** Transmitter output for UART1.
		O	**PWM4 —** Pulse Width Modulator output 4.
		I	**AD1[1] —** ADC 1, input 1.

Table 3. Pin description LPC2158 *…continued*

Symbol	Pin	Type	Description
V_{DD}	11, 27, 33	I	**3.3 V power supply:** This is the power supply voltage for the core and I/O ports.
V_{DDA}	96	I	**Analog 3.3 V power supply:** This should be nominally the same voltage as V_{DD} but should be isolated to minimize noise and error. This voltage is only used to power the on-chip ADC(s) and DAC.
$V_{DD(LCD)}$	38	I	**1.8 V to 5.5 V power supply:** Power supply voltage for the PCF8576D.
V_{LCD}	41	I	**LCD power supply:** LCD voltage.
VREF	89	I	**ADC reference voltage:** This should be nominally less than or equal to the V_{DD} voltage but should be isolated to minimize noise and error. Level on this pin is used as a reference for ADC(s) and DAC.
VBAT	31	I	**RTC power supply voltage:** 3.3 V on this pin supplies the power to the RTC.
SDA_LCD	34	I/O	**SDA LCD —** I^2C-bus data signal for the LCD controller.
SCL_LCD	35	I	**SCL LCD —** I^2C-bus clock signal for the LCD controller.
$\overline{SYNC}$	36	I/O	**$\overline{SYNC}$ —** cascade synchronization input/output
CLK	37	I/O	**CLK —** external clock input/output
BP0 to BP3	42 to 45	O	**BP0 to BP3:** LCD backplane outputs.
S0 to S31	46 to 77	O	**S0 to S31:** LCD segment outputs.

[1] 5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control.

[2] 5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control. If configured for an input function, this pad utilizes built-in glitch filter that blocks pulses shorter than 3 ns.

[3] Open-drain 5 V tolerant digital I/O I^2C-bus 400 kHz specification compatible pad. It requires external pull-up to provide an output functionality.

[4] 5 V tolerant pad providing digital I/O (with TTL levels and hysteresis and 10 ns slew rate control) and analog input function. If configured for an input function, this pad utilizes built-in glitch filter that blocks pulses shorter than 3 ns. When configured as an ADC input, digital section of the pad is disabled.

[5] 5 V tolerant pad providing digital I/O (with TTL levels and hysteresis and 10 ns slew rate control) and analog output function. When configured as the DAC output, digital section of the pad is disabled.

[6] 5 V tolerant pad with built-in pull-up resistor providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control. The pull-up resistor's value typically ranges from 60 kΩ to 300 kΩ.

[7] Pad is designed in accordance with the Universal Serial Bus (USB) specification, revision 2.0 (Full-speed and Low-speed mode only).

[8] 5 V tolerant pad providing digital input (with TTL levels and hysteresis) function only.

[9] Pad provides special analog functionality.

6. Functional description

6.1 Architectural overview

The ARM7TDMI-S is a general purpose 32-bit microprocessor, which offers high performance and very low power consumption. The ARM architecture is based on Reduced Instruction Set Computer (RISC) principles, and the instruction set and related decode mechanism are much simpler than those of microprogrammed Complex Instruction Set Computers (CISC). This simplicity results in a high instruction throughput and impressive real-time interrupt response from a small and cost-effective processor core.

Pipeline techniques are employed so that all parts of the processing and memory systems can operate continuously. Typically, while one instruction is being executed, its successor is being decoded, and a third instruction is being fetched from memory.

The ARM7TDMI-S processor also employs a unique architectural strategy known as Thumb, which makes it ideally suited to high-volume applications with memory restrictions, or applications where code density is an issue.

The key idea behind Thumb is that of a super-reduced instruction set. Essentially, the ARM7TDMI-S processor has two instruction sets:

- The standard 32-bit ARM set.
- A 16-bit Thumb set.

The Thumb set's 16-bit instruction length allows it to approach twice the density of standard ARM code while retaining most of the ARM's performance advantage over a traditional 16-bit processor using 16-bit registers. This is possible because Thumb code operates on the same 32-bit register set as ARM code.

Thumb code is able to provide up to 65 % of the code size of ARM, and 160 % of the performance of an equivalent ARM processor connected to a 16-bit memory system.

6.2 On-chip flash program memory

The LPC2157/2158 incorporate a 512 kB flash memory system. This memory may be used for both code and data storage. Programming of the flash memory may be accomplished in several ways. It may be programmed In System via the serial port. The application program may also erase and/or program the flash while the application is running, allowing a great degree of flexibility for data storage field firmware upgrades, etc. Due to the architectural solution chosen for an on-chip bootloader, flash memory available for user's code on LPC2157/2158 is 500 kB respectively.

The LPC2157/2158 flash memory provides a minimum of 400000 erase/write cycles and 20 years of data-retention.

6.3 On-chip static RAM

On-chip static RAM may be used for code and/or data storage. The SRAM may be accessed as 8-bit, 16-bit, and 32-bit. The LPC2157/2158 provide 32 kB and 40 kB of static RAM.

FIQ has the highest priority. If more than one request is assigned to FIQ, the VIC combines the requests to produce the FIQ signal to the ARM processor. The fastest possible FIQ latency is achieved when only one request is classified as FIQ, because then the FIQ service routine does not need to branch into the interrupt service routine but can run from the interrupt vector location. If more than one request is assigned to the FIQ class, the FIQ service routine will read a word from the VIC that identifies which FIQ source(s) is (are) requesting an interrupt.

Vectored IRQs have the middle priority. Sixteen of the interrupt requests can be assigned to this category. Any of the interrupt requests can be assigned to any of the 16 vectored IRQ slots, among which slot 0 has the highest priority and slot 15 has the lowest.

Non-vectored IRQs have the lowest priority.

The VIC combines the requests from all the vectored and non-vectored IRQs to produce the IRQ signal to the ARM processor. The IRQ service routine can start by reading a register from the VIC and jumping there. If any of the vectored IRQs are pending, the VIC provides the address of the highest-priority requesting IRQs service routine, otherwise it provides the address of a default routine that is shared by all the non-vectored IRQs. The default routine can read another VIC register to see what IRQs are active.

6.5.1 Interrupt sources

Each peripheral device has one interrupt line connected to the Vectored Interrupt Controller, but may have several internal interrupt flags. Individual interrupt flags may also represent more than one interrupt source.

6.6 Pin connect block

The pin connect block allows selected pins of the microcontroller to have more than one function. Configuration registers control the multiplexers to allow connection between the pin and the on chip peripherals. Peripherals should be connected to the appropriate pins prior to being activated, and prior to any related interrupt(s) being enabled. Activity of any enabled peripheral function that is not mapped to a related pin should be considered undefined.

The Pin Control Module with its pin select registers defines the functionality of the microcontroller in a given hardware environment.

After reset all pins of Port 0 and Port 1 are configured as input with the following exceptions: If debug is enabled, the JTAG pins will assume their JTAG functionality. The pins associated with the I^2C0 and I^2C1 interface are open drain.

6.7 Fast general purpose parallel I/O

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Separate registers allow setting or clearing any number of outputs simultaneously. The value of the output register may be read back, as well as the current state of the port pins.

LPC2157/2158 introduce accelerated GPIO functions over prior LPC2000 devices:

- GPIO registers are relocated to the ARM local bus for the fastest possible I/O timing.

The LPC2158 is equipped with a USB device controller that enables 12 Mbit/s data exchange with a USB host controller. It consists of a register interface, serial interface engine, endpoint buffer memory and DMA controller. The serial interface engine decodes the USB data stream and writes data to the appropriate end point buffer memory. The status of a completed USB transfer or error condition is indicated via status registers. An interrupt is also generated if enabled.

A DMA controller can transfer data between an endpoint buffer and the USB RAM.

6.10.1 Features

- Fully compliant with USB 2.0 Full-speed specification.
- Supports 32 physical (16 logical) endpoints.
- Supports control, bulk, interrupt and isochronous endpoints.
- Scalable realization of endpoints at run time.
- Endpoint maximum packet size selection (up to USB maximum specification) by software at run time.
- RAM message buffer size based on endpoint realization and maximum packet size.
- Supports SoftConnect and GoodLink LED indicator. These two functions are sharing one pin.
- Supports bus-powered capability with low suspend current.
- Supports DMA transfer on all non-control endpoints.
- One duplex DMA channel serves all endpoints.
- Allows dynamic switching between CPU controlled and DMA modes.
- Double buffer implementation for bulk and isochronous endpoints.

6.11 UARTs

The LPC2157/2158 each contain two UARTs. In addition to standard transmit and receive data lines, the UART1 also provides a full modem control handshake interface.

Compared to previous LPC2000 microcontrollers, UARTs in LPC2157/2158 introduce a fractional baud rate generator for both UARTs, enabling these microcontrollers to achieve standard baud rates such as 115200 Bd with any crystal frequency above 2 MHz. In addition, auto-CTS/RTS flow-control functions are fully implemented in hardware.

6.11.1 Features

- 16 B Receive and Transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B and 14 B
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- Transmission FIFO control enables implementation of software (XON/XOFF) flow control on both UARTs.
- LPC2158 UART1 equipped with standard modem interface signals. This module also provides full support for hardware flow control (auto-CTS/RTS).

6.12 I²C-bus serial I/O controller

The LPC2157/2158 each contain two I²C-bus controllers.

The I²C-bus is bidirectional, for inter-IC control using only two wires: a serial clock line (SCL), and a serial data line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver or a transmitter with the capability to both receive and send information (such as memory)). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I²C-bus is a multi-master bus, it can be controlled by more than one bus master connected to it.

The I²C-bus implemented in LPC2157/2158 supports bit rates up to 400 kbit/s (Fast I²C-bus).

6.12.1 Features

- Compliant with standard I²C-bus interface.
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I²C-bus can be used for test and diagnostic purposes.

6.13 SPI serial I/O controller

The LPC2157/2158 each contain one SPI controller. The SPI is a full duplex serial interface, designed to handle multiple masters and slaves connected to a given bus. Only a single master and a single slave can communicate on the interface during a given data transfer. During a data transfer the master always sends a byte of data to the slave, and the slave always sends a byte of data to the master.

6.13.1 Features

- Compliant with SPI specification.
- Synchronous, Serial, Full Duplex, Communication.
- Combined SPI master and slave.
- Maximum data bit rate of one eighth of the input clock rate.

6.14 SSP serial I/O controller

The LPC2157/2158 each contain one Serial Synchronous Port controller (SSP). The SSP controller is capable of operation on a SPI, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. However, only a single master and a single

slave can communicate on the bus during a given data transfer. The SSP supports full duplex transfers, with data frames of 4 bits to 16 bits of data flowing from the master to the slave and from the slave to the master. Often only one of these data flows carries meaningful data.

6.14.1 Features

- Compatible with Motorola's SPI, TI's 4-wire SSI and National Semiconductor's Microwire buses.
- Synchronous serial communication.
- Master or slave operation.
- 8-frame FIFOs for both transmit and receive.
- Four bits to 16 bits per frame.

6.15 General purpose timers/external event counters

The Timer/Counter is designed to count cycles of the peripheral clock (PCLK) or an externally supplied clock and optionally generate interrupts or perform other actions at specified timer values, based on four match registers. It also includes four capture inputs to trap the timer value when an input signal transitions, optionally generating an interrupt. Multiple pins can be selected to perform a single capture or match function, providing an application with 'or' and 'and', as well as 'broadcast' functions among them.

The LPC2157/2158 can count external events on one of the capture inputs if the minimum external pulse is equal or longer than a period of the PCLK. In this configuration, unused capture lines can be selected as regular timer capture inputs, or used as external interrupts.

6.15.1 Features

- A 32-bit timer/counter with a programmable 32-bit prescaler.
- External event counter or timer operation.
- Four 32-bit capture channels per timer/counter that can take a snapshot of the timer value when an input signal transitions. A capture event may also optionally generate an interrupt.
- Four 32-bit match registers that allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.
- Four external outputs per timer/counter corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.

6.16 Watchdog timer

The purpose of the watchdog is to reset the microcontroller within a reasonable amount of time if it enters an erroneous state. When enabled, the watchdog will generate a system reset if the user program fails to 'feed' (or reload) the watchdog within a predetermined amount of time.

6.16.1 Features

- Internally resets chip if not periodically reloaded.
- Debug mode.
- Enabled by software but requires a hardware reset or a watchdog reset/interrupt to be disabled.
- Incorrect/Incomplete feed sequence causes reset/interrupt if enabled.
- Flag to indicate watchdog reset.
- Programmable 32-bit timer with internal prescaler.
- Selectable time period from ($T_{cy(PCLK)} \times 256 \times 4$) to ($T_{cy(PCLK)} \times 2^{32} \times 4$) in multiples of $T_{cy(PCLK)} \times 4$.

6.17 Real-time clock

The RTC is designed to provide a set of counters to measure time when normal or idle operating mode is selected. The RTC has been designed to use little power, making it suitable for battery powered systems where the CPU is not running continuously (Idle mode).

6.17.1 Features

- Measures the passage of time to maintain a calendar and clock.
- Ultra-low power design to support battery powered systems.
- Provides Seconds, Minutes, Hours, Day of Month, Month, Year, Day of Week, and Day of Year.
- Can use either the RTC dedicated 32 kHz oscillator input or clock derived from the external crystal/oscillator input at XTAL1. Programmable reference clock divider allows fine adjustment of the RTC.
- Dedicated power supply pin can be connected to a battery or the main 3.3 V.

6.18 Pulse width modulator

The PWM is based on the standard timer block and inherits all of its features, although only the PWM function is pinned out on the LPC2157/2158. The timer is designed to count cycles of the peripheral clock (PCLK) and optionally generate interrupts or perform other actions when specified timer values occur, based on seven match registers. The PWM function is also based on match register events.

The ability to separately control rising and falling edge locations allows the PWM to be used for more applications. For instance, multi-phase motor control typically requires three non-overlapping PWM outputs with individual control of all three pulse widths and positions.

6.21.11 Output bank selector

The LCD controller includes a RAM bank switching feature in the static and 1:2 drive modes. In the static drive mode, the BANK SELECT command may request the contents of bit 2 to be selected for display instead of the contents of bit 0. In 1:2 mode, the contents of bits 2 and 3 may be selected instead of bits 0 and 1. This allows display information to be prepared in an alternative bank and then selected for display when it is assembled.

6.21.12 Input bank selector

The input bank selector loads display data into the display RAM based on the selected LCD drive configuration. The BANK SELECT command can be used to load display data in bit 2 in static drive mode or in bits 2 and 3 in 1:2 mode. The input bank selector functions are independent of the output bank selector.

6.21.13 Blinker

The LCD controller has a very versatile display blinking capability. The whole display can blink at a frequency selected by the BLINK command. Each blink frequency is a multiple integer value of the clock frequency; the ratio between the clock frequency and blink frequency depends on the blink mode selected, as shown in Table 5.

An additional feature allows an arbitrary selection of LCD segments to be blinked in the static and 1:2 drive modes. This is implemented without any communication overheads by the output bank selector which alternates the displayed data between the data in the display RAM bank and the data in an alternative RAM bank at the blink frequency. This mode can also be implemented by the BLINK command.

The entire display can be blinked at a frequency other than the nominal blink frequency by sequentially resetting and setting the display enable bit E at the required rate using the MODE SET command.

Table 5. Blinking frequencies

Blink mode	Normal operating mode ratio	Normal blink frequency
Off	-	blinking off
2 Hz	$f_{osc(ctrl)LCD}/768$	2 Hz
1 Hz	$f_{osc(ctrl)LCD}/1536$	1 Hz
0.5 Hz	$f_{osc(ctrl)LCD}/3072$	0.5 Hz

Blink modes 0.5 Hz, 1 Hz and 2 Hz, and nominal blink frequencies 0.5 Hz, 1 Hz and 2 Hz correspond to an oscillator frequency ($f_{osc(ctrl)LCD}$) of 1536 Hz at pin CLK. The oscillator frequency range is 397 Hz to 3046 Hz.

6.21.13.1 I^2C-bus controller

The LCD controller acts as an I^2C-bus slave receiver. In the LPC2157/2158 the hardware subaddress inputs A0, A1 and A2 are tied to V_{SS} setting the hardware subaddress = 0.

6.21.14 Input filters

To enhance noise immunity in electrically adverse environments, RC low-pass filters are provided on the SDA and SCL lines.

6.21.15 I²C-bus slave addresses

The I²C-bus slave address is 0111 0000. The LCD controller is a write-only device and will not respond to a read access.

7. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage (core and external rail)			–0.5	+3.6	V
V_{DDA}	analog 3.3 V pad supply voltage			–0.5	+4.6	V
$V_{i(VBAT)}$	input voltage on pin VBAT	for the RTC		–0.5	+4.6	V
$V_{i(VREF)}$	input voltage on pin VREF			–0.5	+4.6	V
V_{IA}	analog input voltage	on ADC related pins		–0.5	+5.1	V
V_I	input voltage	5 V tolerant I/O pins; only valid when the V_{DD} supply voltage is present	[2]	–0.5	+6.0	V
		other I/O pins	[2][3]	–0.5	V_{DD} + 0.5	V
I_{DD}	supply current	per supply pin	[4]	-	100	mA
I_{SS}	ground current	per ground pin	[4]	-	100	mA
T_{stg}	storage temperature		[5]	–65	+150	°C
$P_{tot(pack)}$	total power dissipation (per package)	based on package heat transfer, not device power consumption		-	1.5	W

[1] The following applies to the Limiting values:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

[2] Including voltage on outputs in 3-state mode.

[3] Not to exceed 4.6 V.

[4] The peak current is limited to 25 times the corresponding maximum current.

[5] Dependent on package type.

8. Static characteristics

Table 7. Static characteristics

T_{amb} = −40 °C to +85 °C for commercial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
V_{DD}	supply voltage		[2]	3.0	3.3	3.6	V
V_{DDA}	analog 3.3 V pad supply voltage			3.0	3.3	3.6	V
$V_{i(VBAT)}$	input voltage on pin VBAT		[3]	2.0	3.3	3.6	V
$V_{i(VREF)}$	input voltage on pin VREF			2.5	3.3	V_{DDA}	V
Standard port pins, $\overline{\text{RESET}}$, RTCK							
I_{IL}	LOW-level input current	V_I = 0 V; no pull-up		-	-	3	µA
I_{IH}	HIGH-level input current	$V_I = V_{DD}$; no pull-down		-	-	3	µA
I_{OZ}	OFF-state output current	V_O = 0 V; $V_O = V_{DD}$; no pull-up/down		-	-	3	µA
I_{latch}	I/O latch-up current	$-(0.5V_{DD}) < V_I < (1.5V_{DD})$; T_j < 125 °C		-	-	100	mA
V_I	input voltage	pin configured to provide a digital function	[4][5][6][7]	0	-	5.5	V
V_O	output voltage	output active		0	-	V_{DD}	V
V_{IH}	HIGH-level input voltage			2.0	-	-	V
V_{IL}	LOW-level input voltage			-	-	0.8	V
V_{hys}	hysteresis voltage			0.4	-	-	V
V_{OH}	HIGH-level output voltage	I_{OH} = −4 mA	[8]	V_{DD} − 0.4	-	-	V
V_{OL}	LOW-level output voltage	I_{OL} = −4 mA	[8]	-	-	0.4	V
I_{OH}	HIGH-level output current	$V_{OH} = V_{DD}$ − 0.4 V	[8]	−4	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V	[8]	4	-	-	mA
I_{OHS}	HIGH-level short-circuit output current	V_{OH} = 0 V	[9]	-	-	−45	mA
I_{OLS}	LOW-level short-circuit output current	$V_{OL} = V_{DDA}$	[9]	-	-	50	mA
I_{pd}	pull-down current	V_I = 5 V	[10]	10	50	150	µA
I_{pu}	pull-up current	V_I = 0 V	[11]	−15	−50	−85	µA
		$V_{DD} < V_I$ < 5 V	[10]	0	0	0	µA

Table 7. Static characteristics *…continued*

T_{amb} = −40 °C to +85 °C for commercial applications, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
$V_{o(XTAL2)}$	output voltage on pin XTAL2		0	-	1.8	V
$V_{i(RTCX1)}$	input voltage on pin RTCX1		0	-	1.8	V
$V_{o(RTCX2)}$	output voltage on pin RTCX2		0	-	1.8	V
USB pins						
I_{OZ}	OFF-state output current	0 V < V_I < 3.3 V	-	-	±10	µA
V_{BUS}	bus supply voltage		-	-	5.25	V
V_{DI}	differential input sensitivity voltage	|(D+) − (D−)|	0.2	-	-	V
V_{CM}	differential common mode voltage range	includes V_{DI} range	0.8	-	2.5	V
$V_{th(rs)se}$	single-ended receiver switching threshold voltage		0.8	-	2.0	V
V_{OL}	LOW-level output voltage	R_L of 1.5 kΩ to 3.6 V	-	-	0.3	V
V_{OH}	HIGH-level output voltage	R_L of 15 kΩ to GND	2.8	-	3.6	V
C_{trans}	transceiver capacitance	pin to GND	-	-	20	pF
Z_{DRV}	driver output impedance for driver which is not high-speed capable	steady state drive [15]	29	-	44	Ω
R_{pu}	pull-up resistance	SoftConnect = ON	1.1	-	1.9	kΩ

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] Core and external rail.

[3] The RTC typically fails when $V_{i(VBAT)}$ drops below 1.6 V.

[4] Including voltage on outputs in 3-state mode.

[5] V_{DD} supply voltages must be present.

[6] 3-state outputs go into 3-state mode when V_{DD} is grounded.

[7] Please also see the errata note mentioned in errata sheet.

[8] Accounts for 100 mV voltage drop in all supply lines.

[9] Allowed as long as the current limit does not exceed the maximum current allowed by the device.

[10] Minimum condition for V_I = 4.5 V, maximum condition for V_I = 5.5 V.

[11] Applies to P1[16] to P1[31].

[12] On pin VBAT.

[13] Optimized for low battery consumption.

[14] To V_{SS}.

[15] Includes external resistors of 18 Ω ±1 % on D+ and D−.

Table 8. ADC static characteristics

V_{DDA} = 2.5 V to 3.6 V; T_{amb} = −40 °C to +85 °C unless otherwise specified; ADC frequency 4.5 MHz.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IA}	analog input voltage			0	-	V_{DDA}	V
C_{ia}	analog input capacitance			-	-	1	pF
E_D	differential linearity error	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[1][2]	-	-	±1	LSB
$E_{L(adj)}$	integral non-linearity	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[3]	-	-	±2	LSB
E_O	offset error	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[4]	-	-	±3	LSB
E_G	gain error	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[5]	-	-	±0.5	%
E_T	absolute error	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[6]	-	-	±4	LSB
R_{vsi}	voltage source interface resistance		[7]	-	-	40	kΩ

[1] The ADC is monotonic, there are no missing codes.

[2] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 7.

[3] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 7.

[4] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 7.

[5] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 7.

[6] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See Figure 7.

[7] See Figure 8.

9.1 Timing

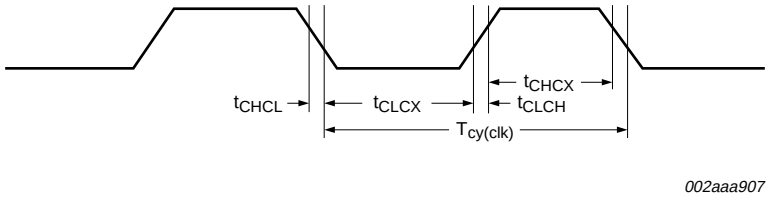


Fig 9. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

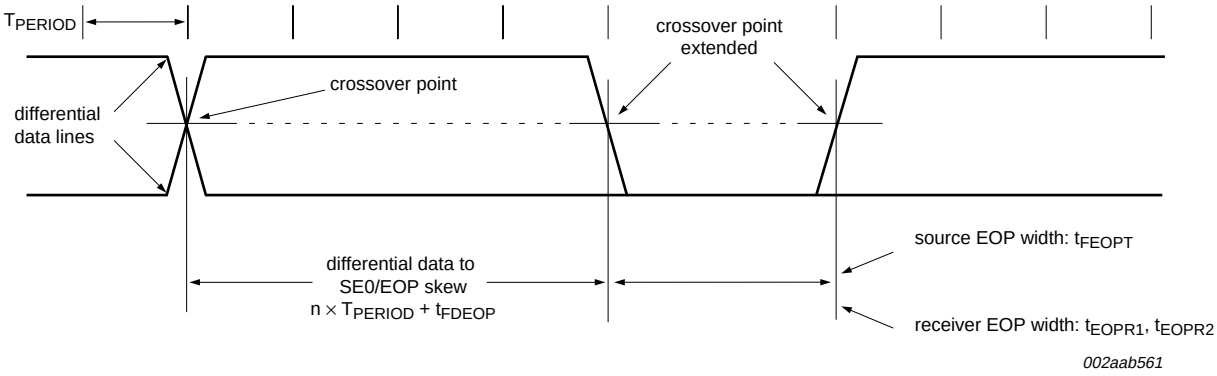


Fig 10. Differential data-to-EOP transition skew and EOP width

10. Application information

10.1 Suggested USB interface solutions

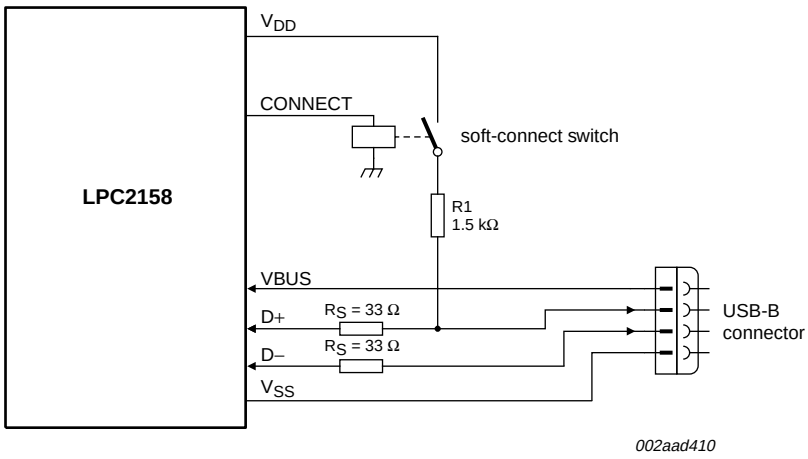
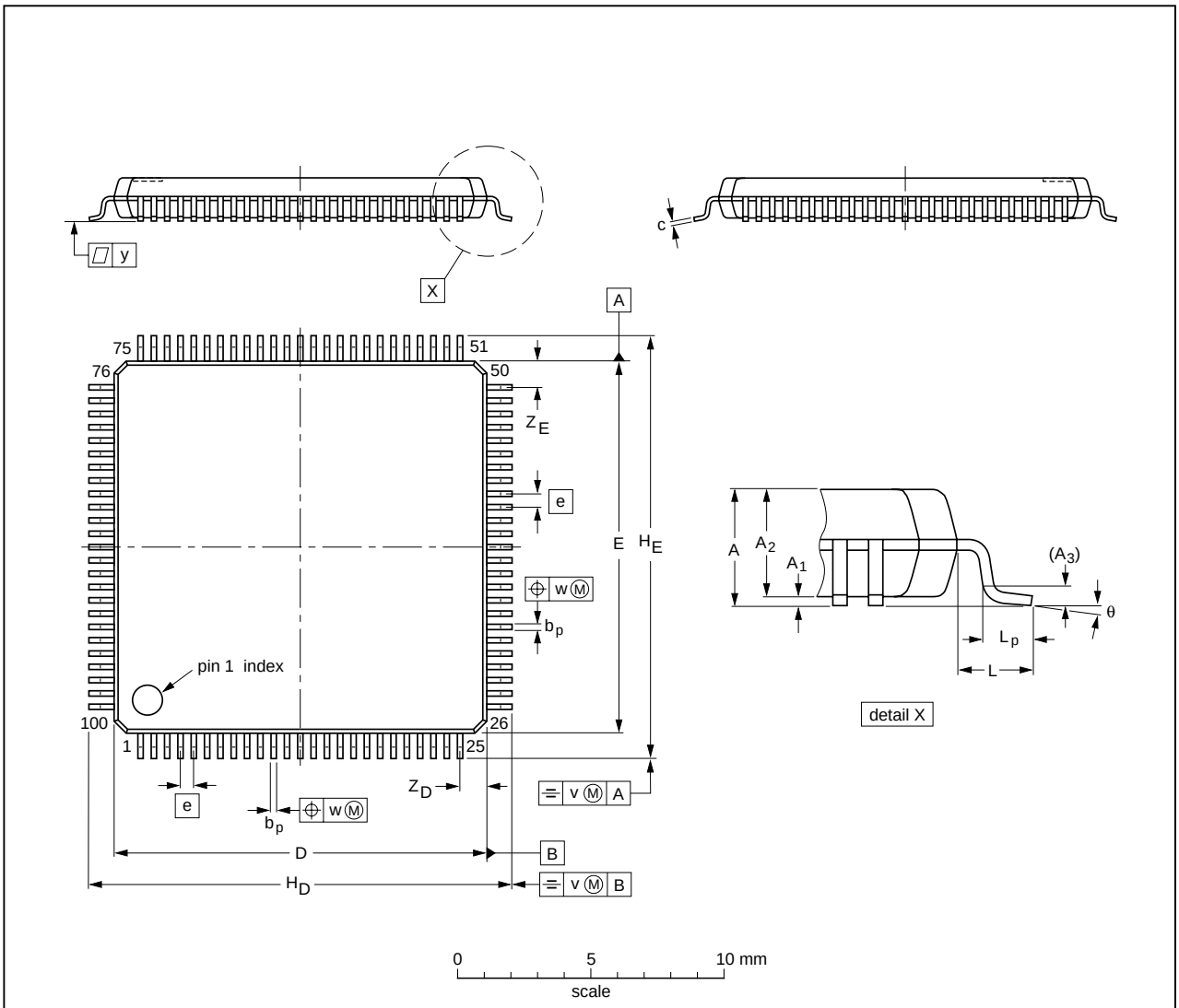


Fig 11. LPC2158 USB interface using the CONNECT function on pin 17

11. Package outline

LQFP100: plastic low profile quad flat package; 100 leads; body 14 x 14 x 1.4 mm **SOT407-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.27 0.17	0.20 0.09	14.1 13.9	14.1 13.9	0.5	16.25 15.75	16.25 15.75	1	0.75 0.45	0.2	0.08	0.08	1.15 0.85	1.15 0.85	7^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT407-1	136E20	MS-026				~~00-02-01~~ 03-02-20

Fig 13. Package outline SOT407-1 (LQFP100)

14. Legal information

14.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

14.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

14.3 Disclaimers

General — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

14.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

I^2C-bus — logo is a trademark of NXP B.V.

GoodLink — is a trademark of ST-NXP Wireless.

SoftConnect — is a trademark of ST-NXP Wireless.

15. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**

16. Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 9 February 2009
Document identifier: LPC2157_2158_2